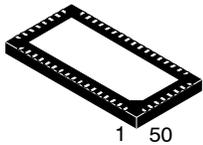


# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

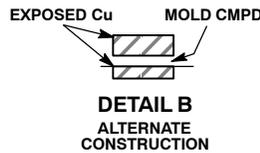
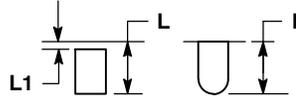
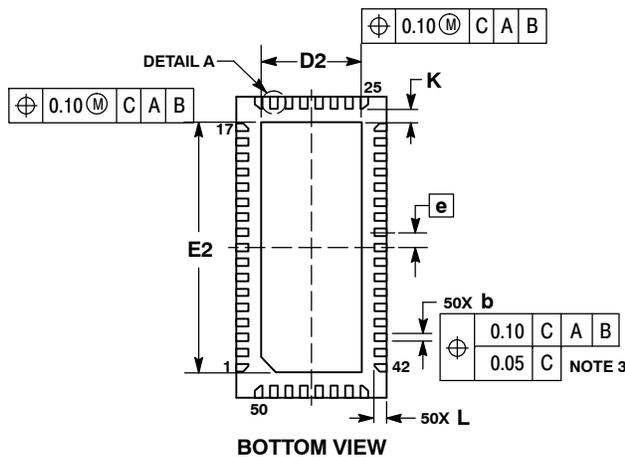
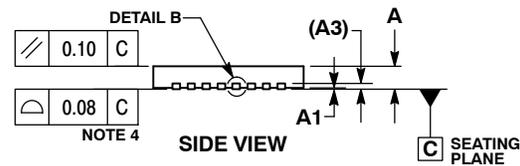
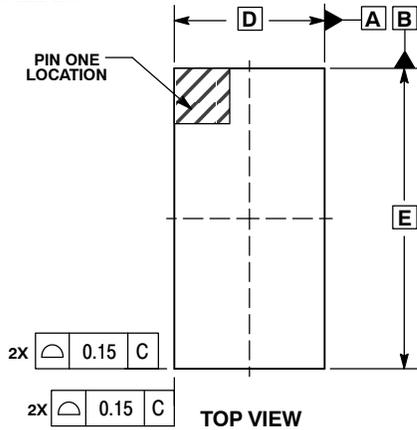
ON Semiconductor®



SCALE 2:1

**QFN50 10x5, 0.5P**  
CASE 485BW  
ISSUE O

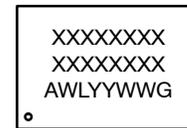
DATE 21 JUL 2011



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSIONS: MILLIMETERS.
  3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25mm FROM TERMINAL TIP
  4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20 REF	
b	0.18	0.30
D	5.00 BSC	
D2	3.20	3.45
E	10.00 BSC	
E2	8.20	8.45
e	0.50 BSC	
K	0.20 MIN	
L	0.30	0.50
L1	0.00	0.15

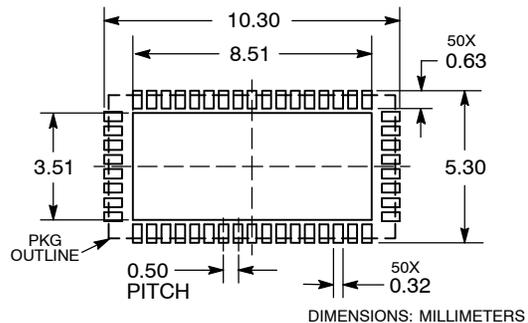
### GENERIC MARKING DIAGRAM\*



- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

### RECOMMENDED SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>QFN50, 10x5, 0.5MM PITCH</b>	<b>PAGE 1 OF 2</b>

